

Data sheet	
status	Product specification
date of issue	June 1990

FCB61C65(L/LL)

8 K x 8 Fast CMOS low-power static RAM

FOR DETAILED INFORMATION SEE RELEVANT DATA BOOK OR DATA SHEET

FEATURES

- Operating supply voltage
5 V ± 10%
- Inputs and outputs ESD protected
- Automatic power-down after a completed read access
- Access time: 55 ns and 70 ns
- Low current consumption:

active	70 mA max.
standby (TTL)	3 mA max.
standby (CMOS)	100 µA max. (L-version)
standby (CMOS)	1 µA max. (LL-version)
- Suitable for battery back-up operation: (FCB61C65L/LL only)

data retention voltage	2 V min.
data retention current	50 µA max. (L-version)
data retention current	1 µA max. (LL-version)
- Latched data outputs giving stable data between consecutive accesses
- Easy memory expansion
- Common data I/O interface
- All inputs and outputs TTL and CMOS compatible
- All inputs have a Schmitt trigger switching action
- Three-state outputs
- Operating temperature 0 °C to +70 °C

GENERAL DESCRIPTION

The FCB61C65(L/LL) is a 65536-bit fast, low-power, static random access memory organized as 8192 words of 8 bits each.

The chip enable inputs $\overline{CE1}$ and $CE2$ are available for memory expansion and to control the low-power/standby mode.

The device operates from a 5 V power supply and has an access time of 55 ns and 70 ns.

The FCB61C65(L/LL) is ideally suited for memory applications where fast access time, low power and ease of use are required.

The FCB61C65(L/LL) is a CMOS device which uses a 6 transistor memory cell.

The IC is fabricated in a CMOS double-metal single-poly process using ion-implanted silicon gate technology.

ORDERING AND PACKAGE INFORMATION

EXTENDED TYPE NUMBER	PACKAGE			
	PINS	PIN POSITION	MATERIAL	CODE
FCB61C65 (L/LL)-XXP	28	DIL (600 mil)	plastic	SOT117
FCB61C65 (L/LL)-XXT	28	SO28XL (330mil)	plastic	SOT213

8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

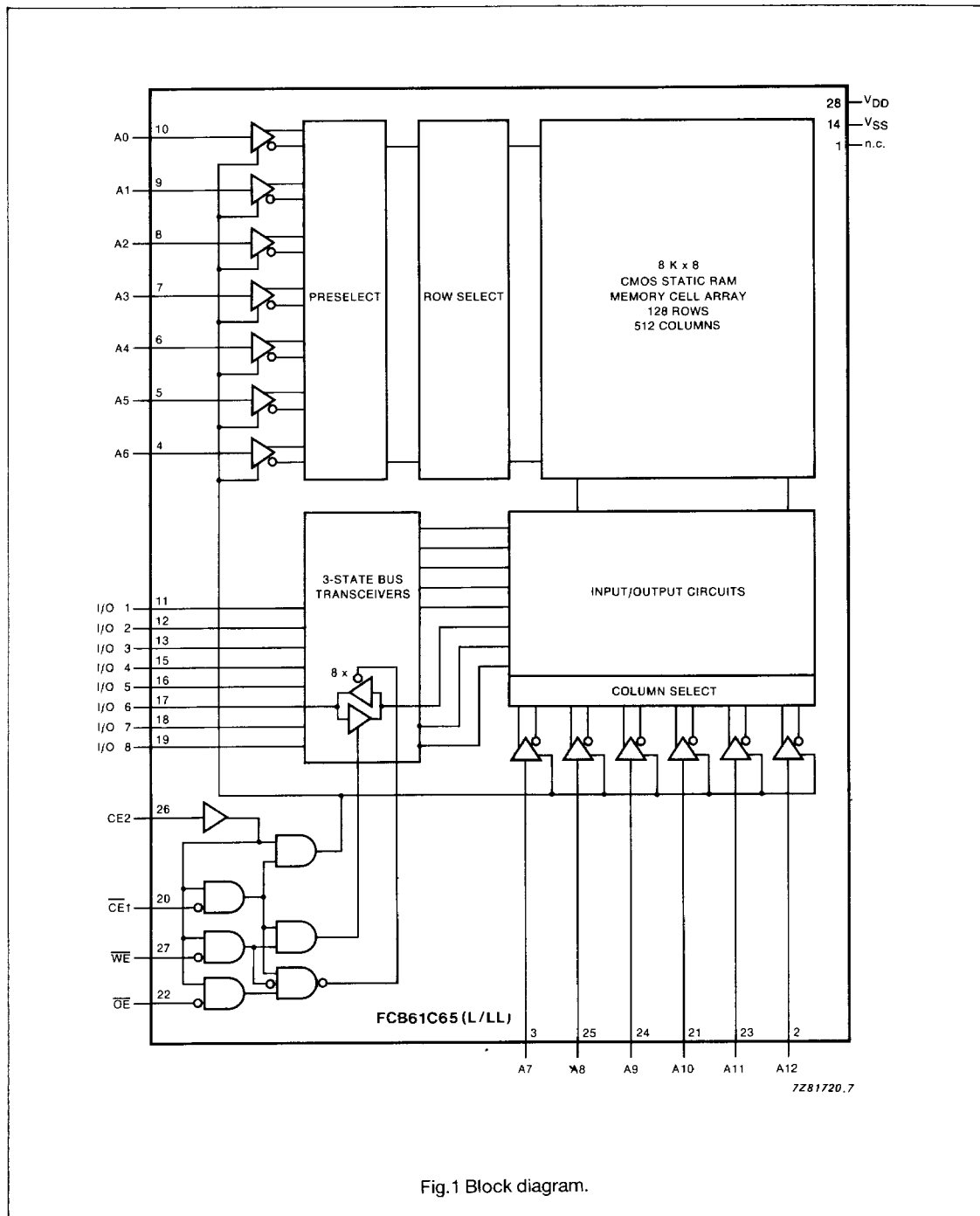


Fig.1 Block diagram.

8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

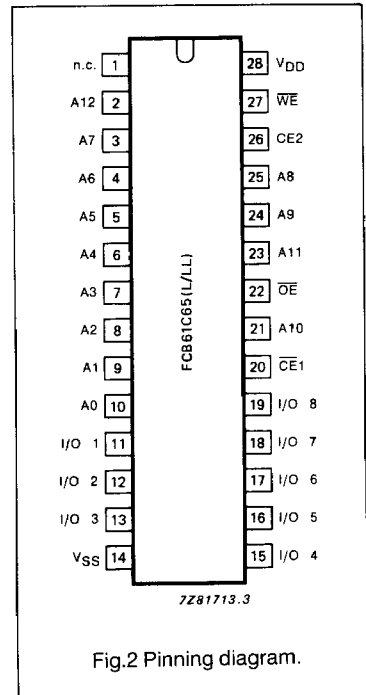
TRUTH TABLE

CE1	CE2	OE	WE	MODE	I _{DD}	I/O PIN	REF. CYCLE
H	X	X	X	not selected	I _{SB} *	HIGH Z	
X	L	-X	X	not selected	I _{SB} *	HIGH Z	
L	H	L	H	read	I _{DD} /I _{DD1} *	D OUT	read
L	H	H	L	write	I _{DD}	D IN	write
L	H	L	L	write	I _{DD}	D IN	write
L	H	H	H	ready-read	I _{DD} /I _{DD1} *	HIGH Z	

* Including L/LL versions if input levels are CMOS.

PINNING

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
A12	2	address input
A7 to A0	3 to 10	address inputs
I/O 1 to I/O 3	11 to 13	data inputs/outputs
V _{SS}	14	ground
I/O 4 to I/O 8	15 to 19	data inputs/outputs
CE1	20	chip enable 1
A10	21	address input
OE	22	output enable
A11, A9, A8	23 to 25	address inputs
CE2	26	chip enable 2
WE	27	write enable
V _{DD}	28	+5 V supply



8 K x 8 Fast CMOS low-power static RAM**FCB61C65(L/LL)****DC CHARACTERISTICS**

$V_{DD} = 5\text{ V} \pm 10\%$; $T_{amb} = 0$ to $70\text{ }^{\circ}\text{C}$. Typical readings taken at $V_{DD} = 5\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$. All voltages are referenced to V_{SS} (0 V) unless otherwise specified. DC characteristics are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{LI}	input leakage current	$V_I = V_{SS}$ to V_{DD}	-1	-	1	μA
I_{LO}	output leakage current	$\overline{CE}1$ or $\overline{OE} = V_{IH}$ or $CE2 = V_{IL}$; $V_{I/O} = V_{SS}$ to V_{DD}	-1	-	1	μA
I_{DD}	average operating current	cycle time 55 ns; 100% duty factor; note 1 $I_{I/O} = 0\text{ mA}$	-	40	70	mA
I_{DD}	average operating current	cycle time 70 ns; 100% duty factor; note 1 $I_{I/O} = 0\text{ mA}$	-	35	60	mA
I_{DD1}	DC operating current	$\overline{WE} = V_{IH}$; $I_{I/O} = 0\text{ mA}$; $f = 0\text{ Hz}$ $\overline{WE} = \text{CMOSH}$; $V_I = \text{CMOS}$; note 2	-	3	6	mA
I_{DDL}	FCB61C65L only		-	2	100	μA
I_{DDL}	FCB61C65LL only		-	0.05	1.0	μA
I_{SB}	standby current	$\overline{CE}1 = V_{IH}$ or $CE2 = V_{IL}$ $\overline{CE}1 = \text{CMOSH}$ and $CE2 = \text{CMOS}$ or $CE2 = \text{CMOSL}$	-	1.5	3.0	mA
I_{SBL}	FCB61C65L only		-	2	100	μA
I_{SBL}	FCB61C65LL only		-	0.05	1.0	μA
V_{OL}	output voltage LOW	$I_{OL} = 4\text{ mA}$	-	-	0.4	V
V_{OL}	output voltage LOW	$I_{OL} = 20\text{ }\mu\text{A}$	-	-	0.2	V
V_{OH}	output voltage HIGH	$I_{OH} = -1\text{ mA}$	2.4	-	-	V
V_{OH}	output voltage HIGH	$I_{OH} = -20\text{ }\mu\text{A}$	$V_{DD}-0.2$	-	-	V

Notes to the DC characteristics

- $I_{DD} \leq 50\text{ mA}$ at a cycle time of 100 ns and $\leq 45\text{ mA}$ at a cycle time of 120 ns.
- CMOS = CMOSH: $V_{DD} - 0.2\text{ V} \leq \text{level} \leq V_{DD} + 0.2\text{ V}$ or
CMOSL: $-0.2\text{ V} \leq \text{level} \leq +0.2\text{ V}$.

CAPACITANCES

$f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$ (parameters in this table are sampled and not 100% tested).

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
C_I	input capacitance		8	pF
C_I	CE1, CE2, WE, OE	$V_I = 0\text{ V}$	7	pF
C_I	all other inputs	$V_I = 0\text{ V}$	8	pF
$C_{I/O}$	input/output capacitance	$V_{I/O} = 0\text{ V}$	8	pF

8 K x 8 Fast CMOS low-power static RAM

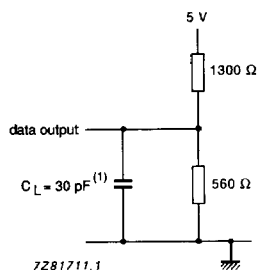
FCB61C65(L/LL)

TIMING CHARACTERISTICS

$V_{DD} = 5 V \pm 10\%$; $T_{amb} = 0$ to $70\text{ }^{\circ}\text{C}$; inputs pulse levels = 0.4 to 2.4 V; input rise and fall times = 5 ns; input and output timing reference levels = 1.5 V and output loading as in Figure 3; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	55 TYPE		70 TYPE		UNIT
			MIN.	MAX.	MIN.	MAX.	
Read cycle							
t_{RC}	read cycle time		55	-	70	-	ns
t_{AA}	address access time		-	55	-	70	ns
t_{ACE}	chip enable access time		-	55	-	70	ns
t_{OE}	output enable access time		-	30	-	35	ns
t_{CLZ}	chip enable to output LOW Z	note 6	5	-	5	-	ns
t_{OLZ}	output enable to output LOW Z	note 6	5	-	5	-	ns
t_{CHZ}	chip disable to output HIGH Z	note 6	-	30	-	30	ns
t_{OHZ}	output disable to output HIGH Z	note 6	-	30	-	30	ns
t_{OH}	output hold time		10	-	10	-	ns
Write cycle							
t_{WC}	write cycle time		55	-	70	-	ns
t_{CW}	chip enable to end of write	note 11	50	-	65	-	ns
t_{AW}	address valid to end of write		50	-	65	-	ns
t_{AS}	address set up time		0	-	0	-	ns
t_{WP}	write pulse width	note 9	30	-	35	-	ns
t_{WR}	write recovery time	note 10	0	-	0	-	ns
t_{WHZ}	write enable to output HIGH Z	note 16	-	20	-	25	ns
t_{DW}	data to write time overlap		25	-	30	-	ns
t_{DH}	data hold from write time		5	-	5	-	ns
t_{ow}	end of write to output LOW Z	note 16	5	-	5	-	ns

Output load



(1) $C_L = 5\text{ pF}$ for t_{CLZ} , t_{CHZ} , t_{WHZ} , t_{OLZ} , t_{OHZ} and t_{ow} .

Fig.3 Output load.

8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

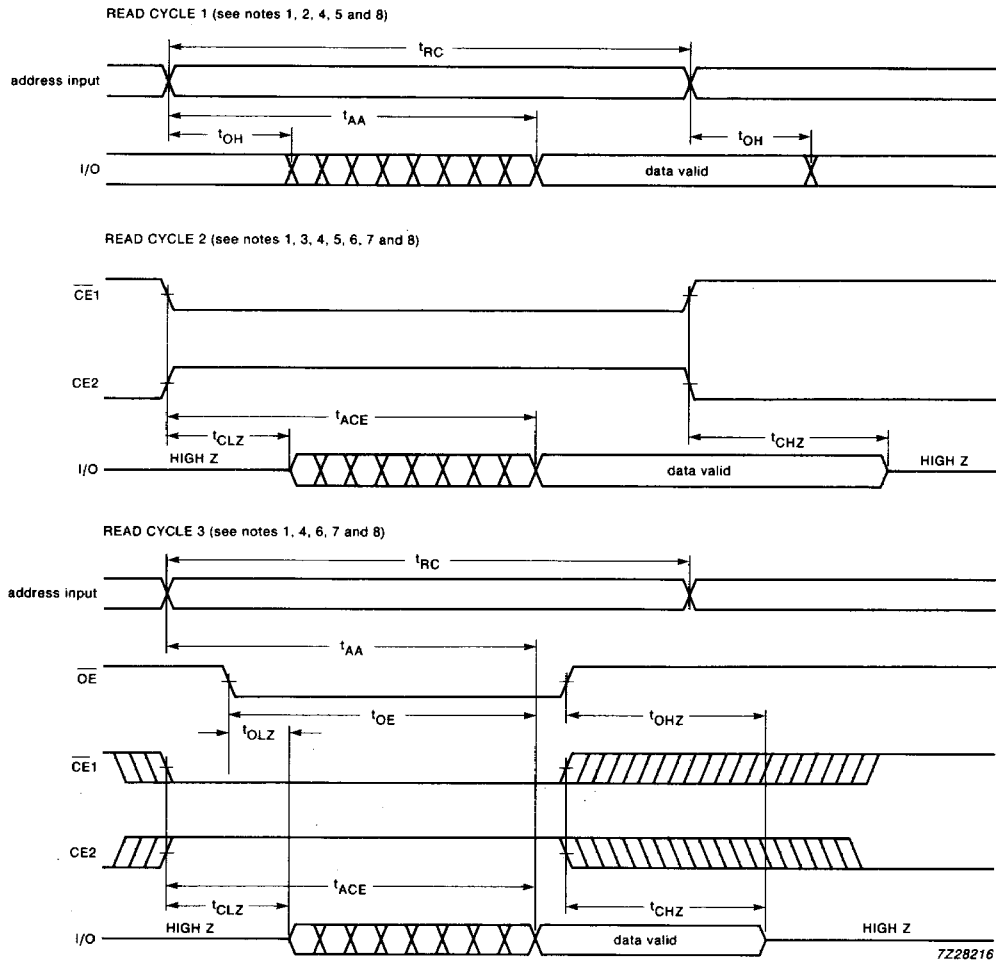


Fig.4 Read cycle timing.

8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

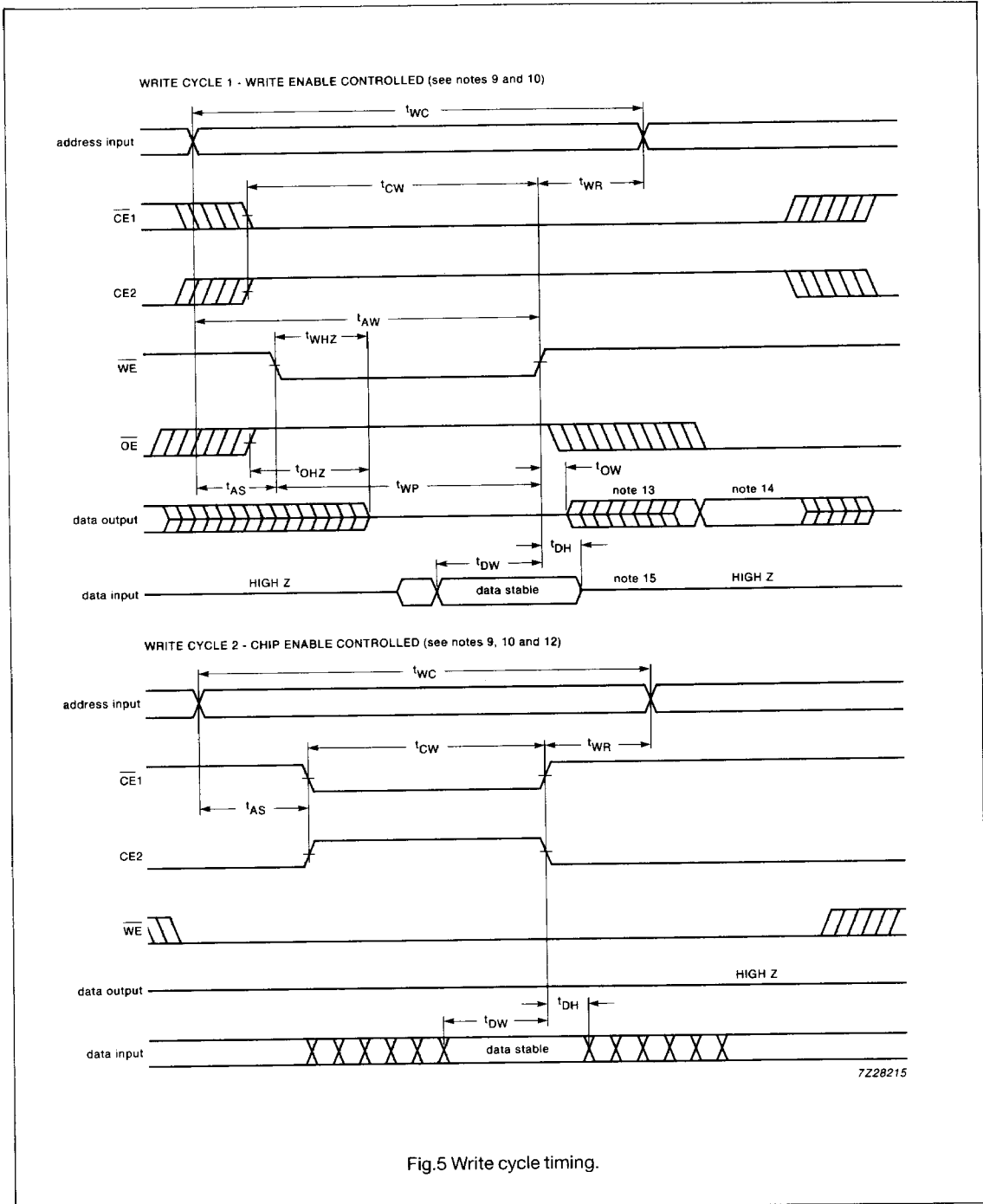


Fig.5 Write cycle timing.

8 K x 8 Fast CMOS low-power static RAM**FCB61C65(L/LL)****Notes to the timing characteristics****Read cycle** (see Fig.4)

1. \overline{WE} is HIGH for read cycle.
2. Device is continuously selected, $\overline{CE1}$ is LOW and CE2 is HIGH.
3. Address is valid prior to or coincident with $\overline{CE1}$ LOW or CE2 HIGH transition.
4. When $\overline{CE1}$ is LOW and CE2 HIGH, the address inputs may not be floating.
5. \overline{OE} is LOW.
6. $C_L = 5$ pF for t_{CLZ} , t_{CHZ} , t_{OLZ} , output transition measured at ± 200 mV from preceding steady state. These parameters are sampled and not 100% tested.
7. t_{CLZ} and t_{ACE} are measured from the last $\overline{CE1}$ going LOW or CE2 going HIGH. t_{CHZ} is measured from the first of $\overline{CE1}$ going HIGH or CE2 going LOW.
8. If D OUT in two consecutive read cycles is the same, D OUT remains stable.

Write cycle (see Fig.5)

9. A write occurs during an overlap of LOW $\overline{CE1}$, a HIGH CE2 and a LOW \overline{WE} .
10. t_{WR} is measured from the earlier of CE2 going to LOW or $\overline{CE1}$ or \overline{WE} going HIGH at the end of a write cycle.
11. If the $\overline{CE1}/CE2$ transition occurs simultaneously to or after the \overline{WE} LOW transition the outputs remain in a high impedance state.
12. \overline{OE} is continuously LOW.
13. D OUT is in the same phase as the write data of this write cycle.
14. D OUT is the read data of the next address.
15. If $\overline{CE1}$ is LOW (CE2 is HIGH) and I/O pins are in the output state during this period then input data signals of opposite phase to the outputs must not be applied.
16. $C_L = 5$ pF for t_{WHZ} and t_{OW} , measured at ± 200 mV from steady state. These parameters are sampled and not 100% tested.

8 K x 8 Fast CMOS low-power static RAM

FCB61C65(L/LL)

DATA RETENTION CHARACTERISTICS FOR LOW POWER/STANDBY MODE

(FCB61C65L/LL only)

 $T_{amb} = 0$ to $+70$ °C; $I_{DRL/LL}$ measurements are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V_{DR}	supply voltage for data retention	$\overline{CE}1 = \text{CMOSH}$ or $CE2 = \text{CMOSL}$ with other $V_i = \text{CMOS}$; note 1	2.0	-	5.5	V
I_{DRL} $I_{DRL/LL}$	supply current during data retention FCB61C65L only FCB61C65LL only	$V_{DR} = 3$ V; $CE2 = \text{CMOSL}$; other $V_i = \text{CMOS}$ or $\overline{CE}1 = \text{CMOSH}$; other $V_i = \text{CMOS}$	- -	2 0.05	50 1	μA μA
Timing						
t_{CDR}	chip disable to data retention time		0	-	-	ns
t_R	recovery time to fully active	note 2	t_{RC}	-	-	ns

Notes to the data retention characteristics

- CMOS = CMOSH: $V_{DR} - 0.2 \text{ V} \leq \text{level} \leq V_{DR} + 0.2 \text{ V}$ or
CMOSL: $-0.2 \text{ V} \leq \text{level} \leq +0.2 \text{ V}$.
- $t_{RC} =$ read cycle time.

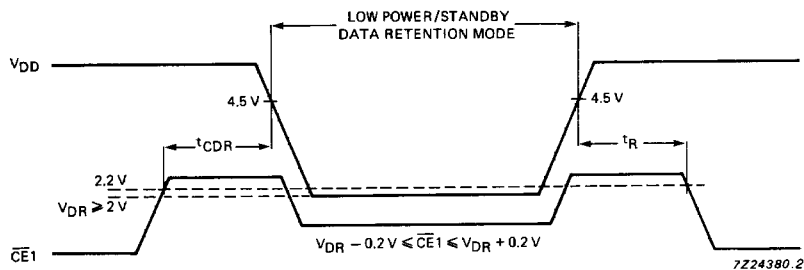
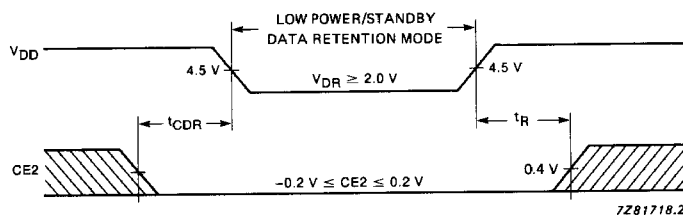
Fig.6 Data retention waveform ($\overline{CE}1$ controlled).

Fig.7 Data retention waveform (CE2 controlled).

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Data sheet	
status	Product specification
date of issue	August 1990

FCF61C65(L/LL)

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FOR DETAILED INFORMATION SEE RELEVANT DATA BOOK OR DATA SHEET

FEATURES

- Operating supply voltage 5 V ± 10%
- Inputs and outputs ESD protected
- Automatic power-down after a completed read access
- Access time: 85 ns
- Low current consumption:
 - active 60 mA max.
 - standby (TTL) 3 mA max.
 - standby (CMOS) 200 µA max. (L-version)
 - standby (CMOS) 4 µA max. (LL-version)
- Suitable for battery back-up operation: (FCF61C65L/LL only)
 - data retention voltage 2 V min.
 - data retention current 100 µA max. (L-version)
 - data retention current 4 µA max. (LL-version)
- Latched data outputs giving stable data between consecutive accesses
- Easy memory expansion
- Common data I/O interface
- All input and outputs TTL and CMOS compatible
- All inputs have a Schmitt trigger switching action
- Three-state outputs
- Operating temperature -40 °C to +85 °C

GENERAL DESCRIPTION

The FCF61C65(L/LL) is a 65536-bit, fast, low-power, static random access memory organized as 8192 words of 8 bits each.

The chip enable inputs $\overline{CE}1$ and $CE2$ are available for memory expansion and to control the lower-power/standby mode.

The device operates from a 5 V power supply and has an access time of 85 ns.

The FCF61C65(L/LL) is ideally suited for memory applications for the extended temperature range of -40 to +85°C where fast access time, low power and ease of use are required.

The FCF61C65(L/LL) is a full CMOS device using a 6 transistor memory cell.

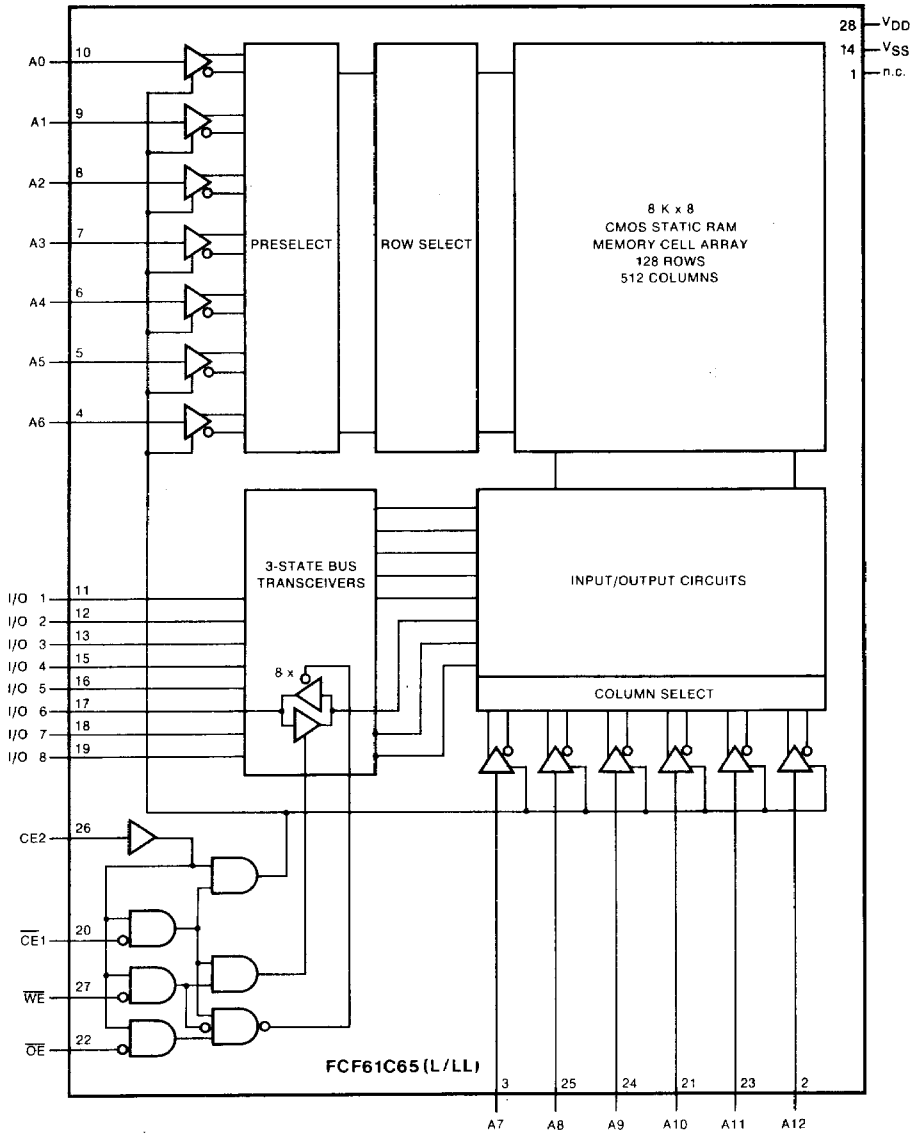
The IC is fabricated in a CMOS double-metal single-poly process using ion-implanted silicon gate technology.

ORDERING AND PACKAGE INFORMATION

EXTENDED TYPE NUMBER	PACKAGE			
	PINS	PIN POSITION	MATERIAL	CODE
FCF61C65 (L/LL)-85T	28	SO28XL(330mil)	plastic	SOT213

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)



7Z26566

Fig.1 Block diagram.

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)

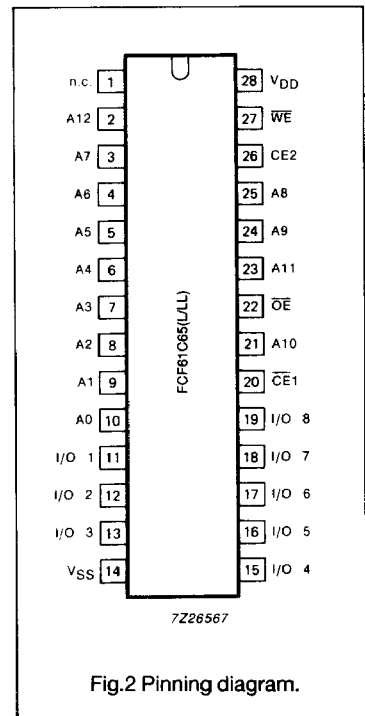
TRUTH TABLE

$\overline{CE1}$	$CE2$	\overline{OE}	WE	MODE	I_{DD}	I/O PIN	REF. CYCLE
H	X	X	X	not selected	I_{SB}^*	HIGH Z	
X	L	X	X	not selected	I_{SB}^*	HIGH Z	
L	H	L	H	read	I_{DD}/I_{DD1}^*	D OUT	read
L	H	H	L	write	I_{DD}	D IN	write
L	H	L	L	write	I_{DD}	D IN	write
L	H	H	H	ready-read	I_{DD}/I_{DD1}^*	HIGH Z	

* Including L/LL versions if input levels are CMOS.

PINNING

SYMBOL	PIN	DESCRIPTION
n.c.	1	not connected
A12	2	address input
A7 to A0	3 to 10	address inputs
I/O 1 to I/O 3	11 to 13	data inputs/outputs
V_{SS}	14	ground
I/O 4 to I/O 8	15 to 19	data inputs/outputs
$\overline{CE1}$	20	chip enable 1
A10	21	address input
\overline{OE}	22	output enable
A11, A9, A8	23 to 25	address inputs
$CE2$	26	chip enable 2
WE	27	write enable
V_{DD}	28	+5 V supply



8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)

DC CHARACTERISTICS

$V_{DD} = 5\text{ V} \pm 10\%$; $T_{amb} = -40$ to $+85\text{ }^{\circ}\text{C}$. Typical readings taken at $V_{DD} = 5\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$. All voltages are referenced to V_{SS} (0 V) unless otherwise specified. DC characteristics are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{LI}	input leakage current	$V_I = V_{SS}$ to V_{DD}	-2	-	2	μA
I_{LO}	output leakage current	$\overline{CE1}$ or $\overline{OE} = V_{IH}$ or $CE2 = V_{IL}$; $V_{I/O} = V_{SS}$ to V_{DD}	-2	-	2	μA
I_{DD}	average operating current	cycle time 85 ns; 100% duty factor; note 1 $I_{I/O} = 0\text{ mA}$	-	35	60	mA
I_{DD1}	DC operating current	$\overline{WE} = V_{IH}$; $I_{I/O} = 0\text{ mA}$; $f = 0\text{ Hz}$	-	3	10	mA
I_{DDL}	FCF61C65L only FCF61C65LL only	$\overline{WE} = \text{CMOSH}$; $V_I = \text{CMOS}$; notes 2 and 3	-	2	200	μA
$I_{D DLL}$			-	0.05	4	μA
I_{SB}	standby current	$\overline{CE1} = V_{IH}$ or $CE2 = V_{IL}$	-	1.5	3.0	mA
I_{SBL}	FCF61C65L only FCF61C65LL only	$\overline{CE1} = \text{CMOSH}$ and $CE2 = \text{CMOS}$ or $CE2 = \text{CMOSL}$; notes 2 and 3	-	2	200	μA
$I_{S DLL}$			-	0.05	4	μA
V_{OL}	output voltage LOW	$I_{OL} = 4\text{ mA}$	-	-	0.4	V
V_{OL}	output voltage LOW	$I_{OL} = 20\text{ }\mu\text{A}$	-	-	0.2	V
V_{OH}	output voltage HIGH	$I_{OH} = -1\text{ mA}$	2.4	-	-	V
V_{OH}	output voltage HIGH	$I_{OH} = -20\text{ }\mu\text{A}$	$V_{DD}-0.2$	-	-	V

Notes to the DC characteristics

- $I_{DD} \leq 55\text{ mA}$ at a cycle time of 100 ns and $\leq 50\text{ mA}$ at a cycle time of 120 ns.
- CMOS = CMOS: $V_{DD} - 0.2\text{ V} \leq \text{level} \leq V_{DD} + 0.2\text{ V}$ or
CMOSL: $-0.2\text{ V} \leq \text{level} \leq +0.2\text{ V}$.
- At $T_{amb} = 70\text{ }^{\circ}\text{C}$: $I_{SBL}/I_{DDL} \leq 100\text{ }\mu\text{A}$ max. and
 $I_{S DLL}/I_{D DLL} \leq 1\text{ }\mu\text{A}$ max.

CAPACITANCES

$f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$ (parameters in this table are sampled and not 100% tested).

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
C_I	input capacitance $\overline{CE1}$, $CE2$, \overline{WE} , \overline{OE} all other inputs	$V_I = 0\text{ V}$	8	pF
C_I		$V_I = 0\text{ V}$	7	pF
$C_{I/O}$	input/output capacitance	$V_{I/O} = 0\text{ V}$	8	pF

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

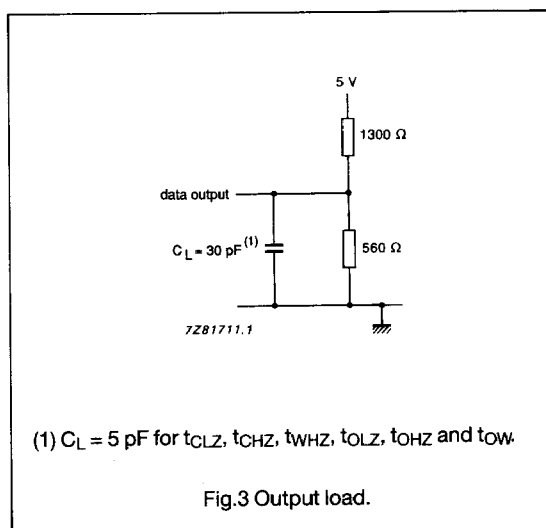
FCF61C65(L/LL)

TIMING CHARACTERISTICS

$V_{DD} = 5\text{ V} \pm 10\%$; $T_{amb} = -40$ to $+85\text{ }^\circ\text{C}$; inputs levels = 0.4 to 2.4 V, input rise and fall times = 5 ns; input and output timing reference levels = 1.5 V and output loading as in Figure 3; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Read cycle					
t_{RC}	read cycle time		85	-	ns
t_{AA}	address access time		-	85	ns
t_{ACE}	chip enable access time		-	85	ns
t_{OE}	output enable access time		-	40	ns
t_{CLZ}	chip enable to output LOW Z	note 6	5	-	ns
t_{OLZ}	output enable to output LOW Z	note 6	5	-	ns
t_{CHZ}	chip disable to output HIGH Z	note 6	-	35	ns
t_{OHZ}	output disable to output HIGH Z	note 6	-	35	ns
t_{OH}	output hold time		10	-	ns
Write cycle					
t_{WC}	write cycle time		85	-	ns
t_{CW}	chip enable to end of write	note 11	70	-	ns
t_{AW}	address valid to end of write		70	-	ns
t_{AS}	address set-up time		0	-	ns
t_{WP}	write pulse width	note 9	40	-	ns
t_{WR}	write recovery time	note 10	5	-	ns
t_{WHZ}	write enable to output HIGH Z	note 16	-	35	ns
t_{DW}	data to write time overlap		35	-	ns
t_{DH}	data hold from write time		5	-	ns
t_{OW}	end of write to output LOW Z	note 16	5	-	ns

Output load



8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)

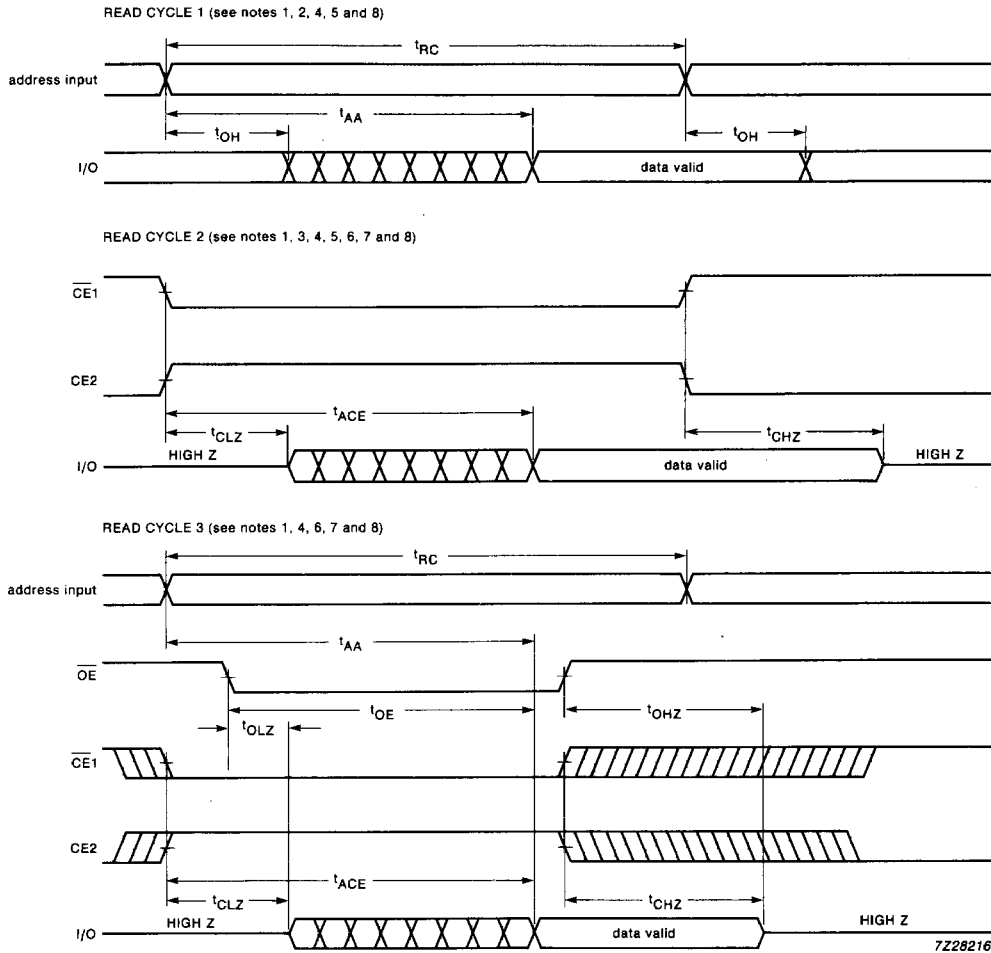


Fig.4 Read cycle timing.

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)

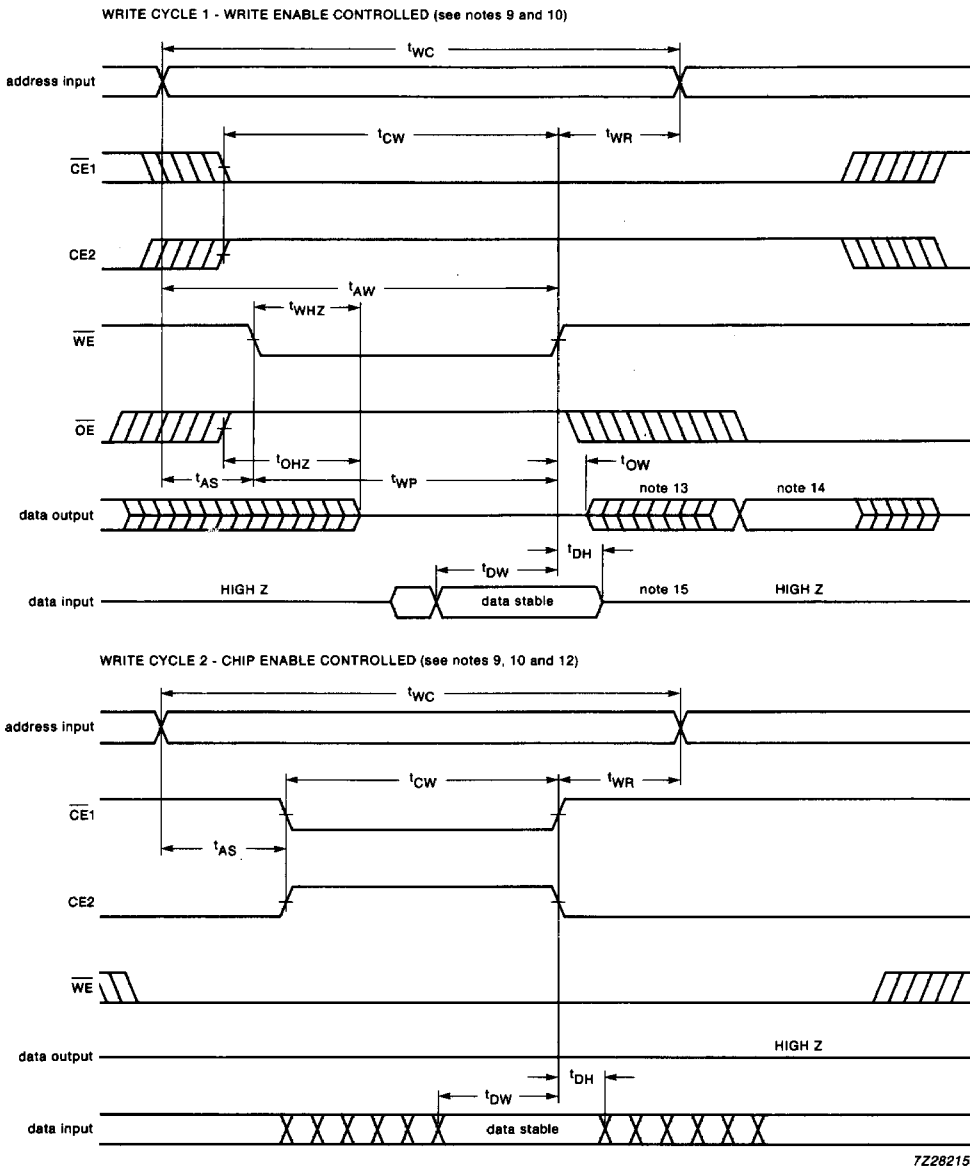


Fig.5 Write cycle timing.

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)**Notes to the timing characteristics****Read cycle** (see Fig.4)

1. \overline{WE} is HIGH for read cycle.
2. Device is continuously selected, $\overline{CE1}$ is LOW and CE2 is HIGH.
3. Address is valid prior to or coincident with $\overline{CE1}$ LOW or CE2 HIGH transition.
4. When $\overline{CE1}$ is LOW and CE2 HIGH, the address inputs may not be floating.
5. \overline{OE} is LOW.
6. $C_L = 5$ pF for t_{CLZ} , t_{CHZ} , t_{OLZ} , output transition measured at ± 200 mV from preceding steady state. These parameters are sampled and not 100% tested.
7. t_{CLZ} and t_{ACE} are measured from the last $\overline{CE1}$ going LOW or CE2 going HIGH. t_{CHZ} is measured from the first of $\overline{CE1}$ going HIGH or CE2 going LOW.
8. If D OUT in two consecutive read cycles is the same, D OUT remains stable.

Write cycle (see Fig.5)

9. A write occurs during an overlap of LOW $\overline{CE1}$, a HIGH CE2 and a LOW \overline{WE} .
10. t_{WR} is measured from the earlier of CE2 going to LOW or $\overline{CE1}$ or \overline{WE} going HIGH at the end of a write cycle.
11. If the $\overline{CE1}/CE2$ transition occurs simultaneously to or after the \overline{WE} LOW transition the outputs remain in a high impedance state.
12. \overline{OE} is continuously LOW.
13. D OUT is in the same phase as the write data of this write cycle.
14. D OUT is the read data of the next address.
15. If $\overline{CE1}$ is LOW (CE2 is HIGH) and I/O pins are in the output state during this period then input data signals of opposite phase to the outputs must not be applied.
16. $C_L = 5$ pF for t_{WHZ} and t_{OW} , measured at ± 200 mV from steady state. These parameters are sampled and not 100% tested.

8 K x 8 Fast CMOS low-power static RAM for extended temperature range

FCF61C65(L/LL)

DATA RETENTION CHARACTERISTICS FOR LOW POWER/STANDBY MODE

(FCF61C65L/LL only)

 $T_{amb} = -40$ to $+85$ °C; $I_{DRL/LL}$ measurements are valid after thermal equilibrium has been established.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
V_{DR}	supply voltage for data retention	$\overline{CE1} = \text{CMOSH}$ or $CE2 = \text{CMOSL}$ with other $V_I = \text{CMOS}$; note 1	2.0	-	5.5	V
I_{DRL} I_{DRL}	supply current during data retention FCF61C65L only FCF61C65LL only	$V_{DR} = 3$ V; $CE2 = \text{CMOSL}$; other $V_I = \text{CMOS}$ or $\overline{CE1} = \text{CMOSH}$; other $V_I = \text{CMOS}$ note 2 note 2	- -	2 0.05	100 4	μA μA
Timing						
t_{CDR}	chip disable to data retention time		0	-	-	ns
t_R	recovery time to fully active	note 3	t_{RC}	-	-	ns

Notes to the data retention characteristics

- CMOS = CMOSH: $V_{DR} - 0.2 \text{ V} \leq \text{level} \leq V_{DR} + 0.2 \text{ V}$ or
CMOSL: $-0.2 \text{ V} \leq \text{level} \leq +0.2 \text{ V}$.
- At $T_{amb} = 70$ °C: $I_{DRL} \leq 50 \mu\text{A}$ and $I_{DRL} \leq 1 \mu\text{A}$.
- t_{RC} = read cycle time.

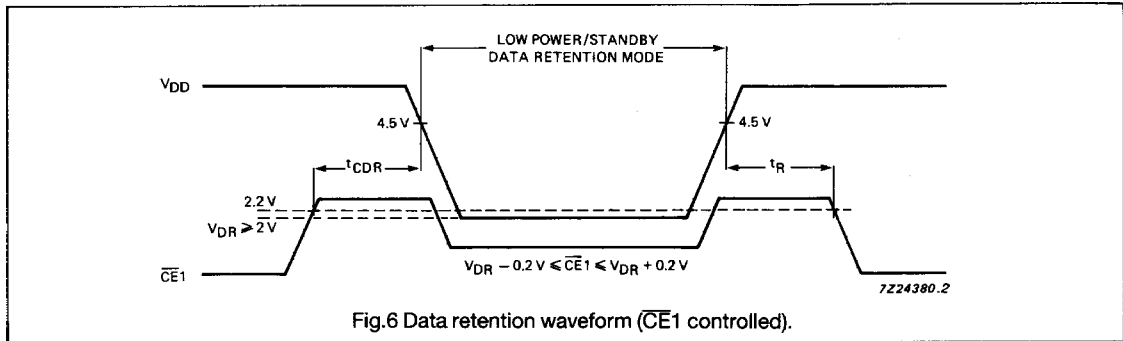


Fig.6 Data retention waveform ($\overline{CE1}$ controlled).

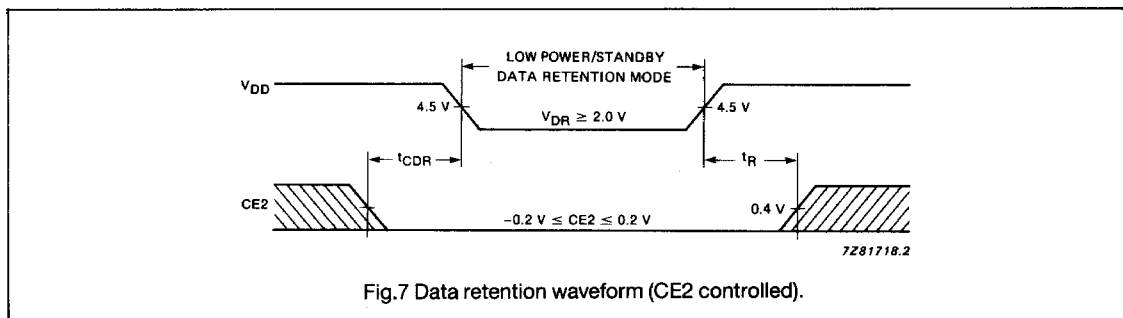


Fig.7 Data retention waveform ($CE2$ controlled).